

PHB95NQ04LT

N-channel TrenchMOS™ logic level FET

Rev. 01 — 11 May 2004

Product data

1. Product profile

1.1 Description

Logic level N-channel enhancement mode field-effect transistor in a plastic package using TrenchMOS™ technology.

1.2 Features

- Logic level threshold
- Low on-state resistance.

1.3 Applications

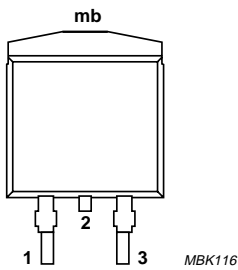
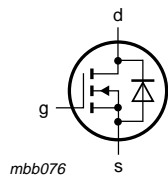
- Motors, lamps, solenoids
- DC-to-DC converters
- Uninterruptible power supplies
- General industrial applications.

1.4 Quick reference data

- $V_{DS} \leq 40$ V
- $I_D \leq 75$ A
- $P_{tot} \leq 157$ W
- $R_{DSon} \leq 7$ m Ω .

2. Pinning information

Table 1: Pinning - SOT404 (D²-PAK), simplified outline and symbol

Pin	Description	Simplified outline	Symbol
1	gate (g)		
2	drain (d) [1]		
3	source (s)		
mb	mounting base; connected to drain (d)	SOT404 (D²-PAK)	

[1] It is not possible to make connection to pin 2 of the SOT404 package.



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3. Ordering information

Table 2: Ordering information

Type number	Package		Version
	Name	Description	
PHB95NQ04LT	D ² -PAK	Plastic single-ended surface mounted package; 3 leads (one lead cropped)	SOT404

4. Limiting values

Table 3: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{DS}	drain-source voltage (DC)	25 °C ≤ T _j ≤ 175 °C	-	40	V
V _{DGR}	drain-gate voltage (DC)	25 °C ≤ T _j ≤ 175 °C; R _{GS} = 20 kΩ	-	40	V
V _{GS}	gate-source voltage (DC)		-	±15	V
I _D	drain current (DC)	T _{mb} = 25 °C; V _{GS} = 10 V; Figure 2 and 3	-	75	A
		T _{mb} = 100 °C; V _{GS} = 10 V; Figure 2	-	75	A
I _{DM}	peak drain current	T _{mb} = 25 °C; pulsed; t _p ≤ 10 μs; Figure 3	-	240	A
P _{tot}	total power dissipation	T _{mb} = 25 °C; Figure 1	-	157	W
T _{stg}	storage temperature		-55	+175	°C
T _j	junction temperature		-55	+175	°C

Source-drain diode

I _S	source (diode forward) current (DC)	T _{mb} = 25 °C	-	75	A
I _{SM}	peak source (diode forward) current	T _{mb} = 25 °C; pulsed; t _p ≤ 10 μs	-	240	A

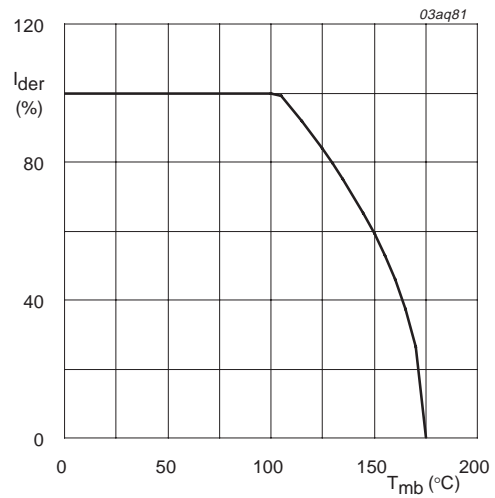
Avalanche ruggedness

E _{DS(AL)S}	non-repetitive drain-source avalanche energy	unclamped inductive load; I _D = 45 A; t _p = 0.17 ms; V _{DD} ≤ 40 V; R _{GS} = 50 Ω; V _{GS} = 10 V; starting T _j = 25 °C	-	200	mJ
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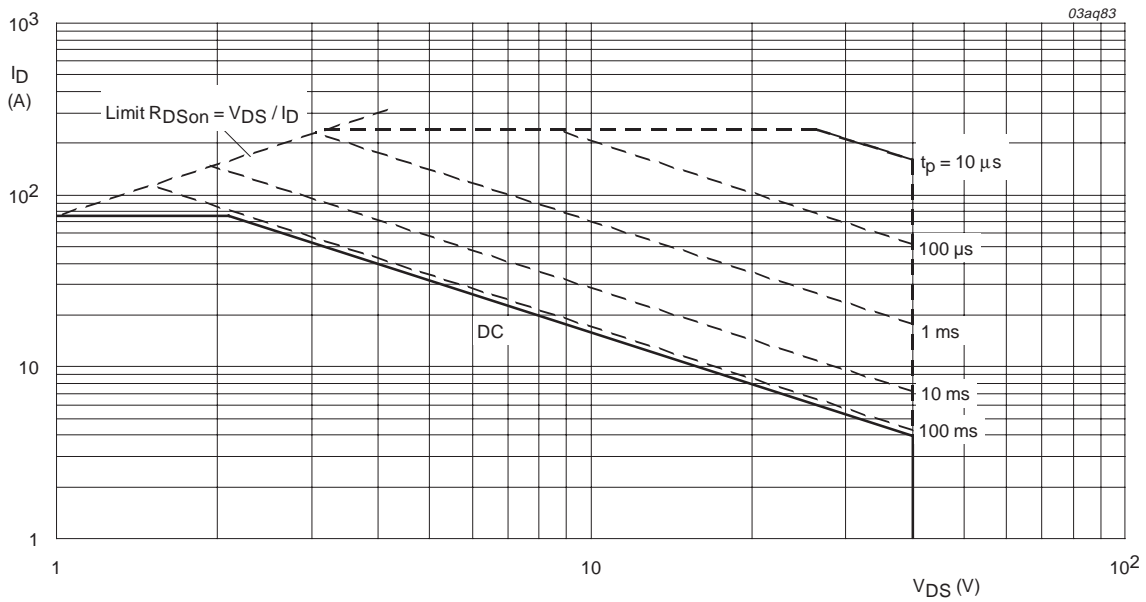
$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$$

Fig 1. Normalized total power dissipation as a function of mounting base temperature.



$$I_{der} = \frac{I_D}{I_{D(25^{\circ}C)}} \times 100\%$$

Fig 2. Normalized continuous drain current as a function of mounting base temperature.



$T_{mb} = 25^{\circ}C$; I_{DM} is single pulse; $V_{GS} = 10 V$

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage.

5. Thermal characteristics

Table 4: Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Figure 4	-	-	0.95	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	mounted on a printed-circuit board; minimum footprint; vertical in still air	-	50	-	K/W

5.1 Transient thermal impedance

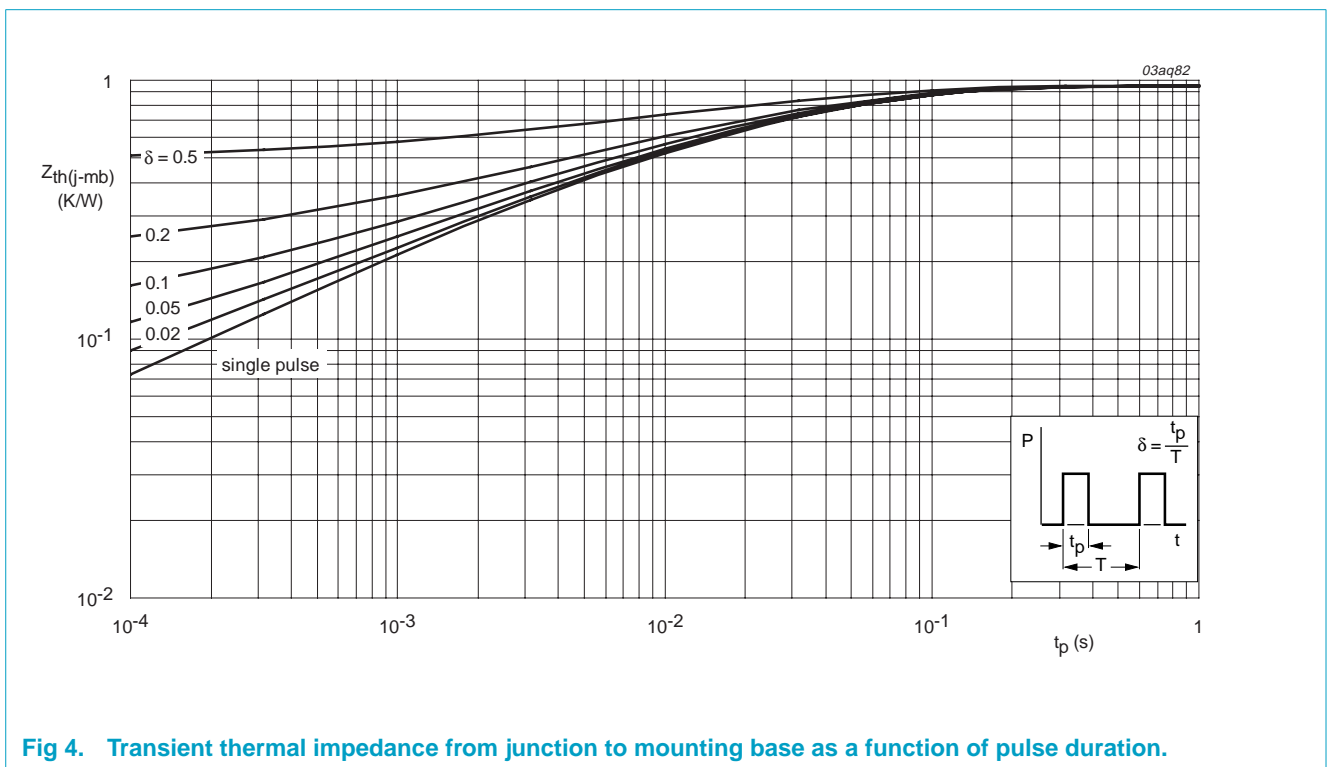
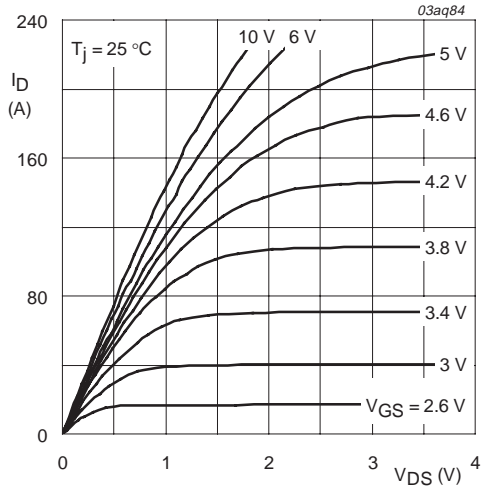


Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration.

6. Characteristics

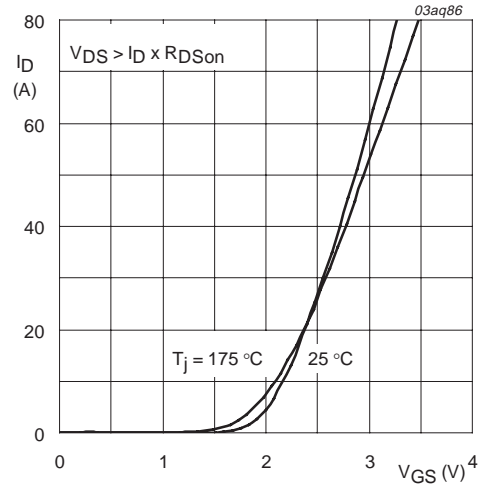
Table 5: Characteristics
T_j = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V _{(BR)DSS}	drain-source breakdown voltage	I _D = 250 μA; V _{GS} = 0 V T _j = 25 °C	40	-	-	V
		T _j = -55 °C	36	-	-	V
V _{GS(th)}	gate-source threshold voltage	I _D = 1 mA; V _{DS} = V _{GS} ; Figure 9 and 10 T _j = 25 °C	1	1.5	2	V
		T _j = 175 °C	0.5	-	-	V
		T _j = -55 °C	-	-	2.2	V
I _{DSS}	drain-source leakage current	V _{DS} = 40 V; V _{GS} = 0 V T _j = 25 °C	-	-	1	μA
		T _j = 175 °C	-	-	500	μA
I _{GSS}	gate-source leakage current	V _{GS} = ±15 V; V _{DS} = 0 V	-	2	100	nA
R _{DS(on)}	drain-source on-state resistance	V _{GS} = 10 V; I _D = 25 A; Figure 7 and 8 T _j = 25 °C	-	6.2	7	mΩ
		T _j = 175 °C	-	11.8	13.3	mΩ
		V _{GS} = 5 V; I _D = 25 A; Figure 7 and 8	-	7.6	9	mΩ
		V _{GS} = 4.5 V; I _D = 25 A	-	-	10	mΩ
Dynamic characteristics						
Q _{g(tot)}	total gate charge	I _D = 25 A; V _{DD} = 32 V; V _{GS} = 5 V; Figure 13	-	32.7	-	nC
Q _{gs}	gate-source charge		-	7.2	-	nC
Q _{gd}	gate-drain (Miller) charge		-	12.4	-	nC
C _{iss}	input capacitance	V _{GS} = 0 V; V _{DS} = 25 V; f = 1 MHz; Figure 11	-	2700	-	pF
C _{oss}	output capacitance		-	450	-	pF
C _{rss}	reverse transfer capacitance		-	210	-	pF
t _{d(on)}	turn-on delay time	V _{DD} = 30 V; R _G = 1.2 Ω;	-	29	-	ns
t _r	rise time	V _{GS} = 5 V; R _G = 10 Ω	-	106	-	ns
t _{d(off)}	turn-off delay time		-	108	-	ns
t _f	fall time		-	89	-	ns
Source-drain diode						
V _{SD}	source-drain (diode forward) voltage	I _S = 25 A; V _{GS} = 0 V; Figure 12	-	0.85	1.2	V
t _{rr}	reverse recovery time	I _S = 20 A; dI _S /dt = -100 A/μs;	-	57	-	ns
Q _r	recovered charge	V _{GS} = 0 V; V _R = 30 V	-	47	-	nC



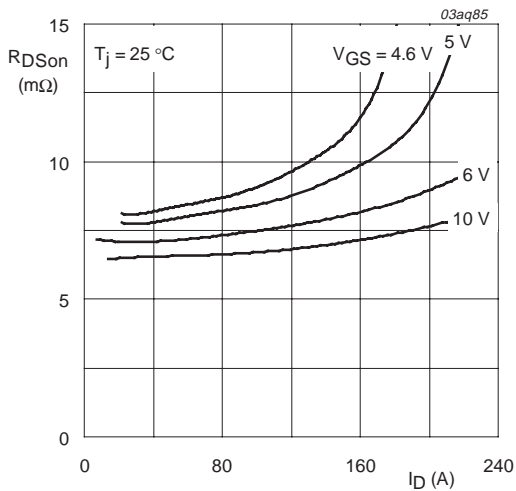
$T_j = 25\text{ }^\circ\text{C}$

Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values.



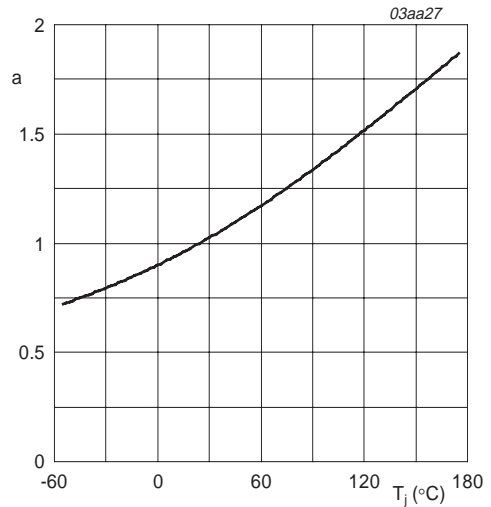
$T_j = 25\text{ }^\circ\text{C}$ and $175\text{ }^\circ\text{C}$; $V_{DS} > I_D \times R_{DSon}$

Fig 6. Transfer characteristics: drain current as a function of gate-source voltage; typical values.



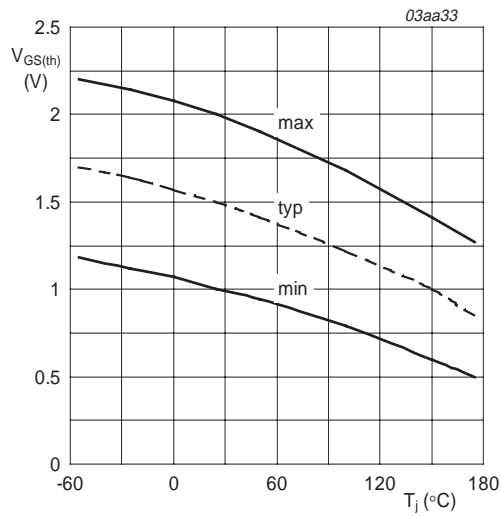
$T_j = 25\text{ }^\circ\text{C}$

Fig 7. Drain-source on-state resistance as a function of drain current; typical values.



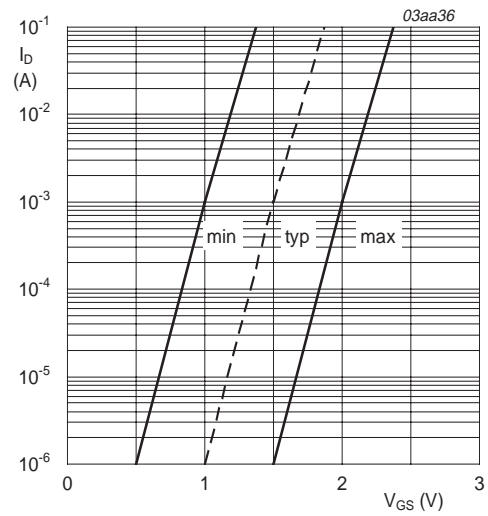
$$a = \frac{R_{DSon}}{R_{DSon}(25^\circ\text{C})}$$

Fig 8. Normalized drain-source on-state resistance factor as a function of junction temperature.



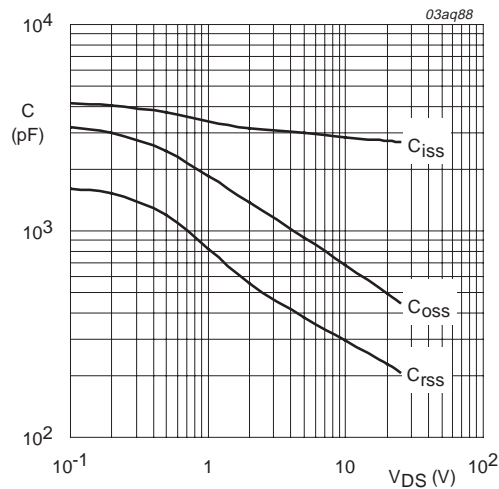
$I_D = 1 \text{ mA}; V_{DS} = V_{GS}$

Fig 9. Gate-source threshold voltage as a function of junction temperature.



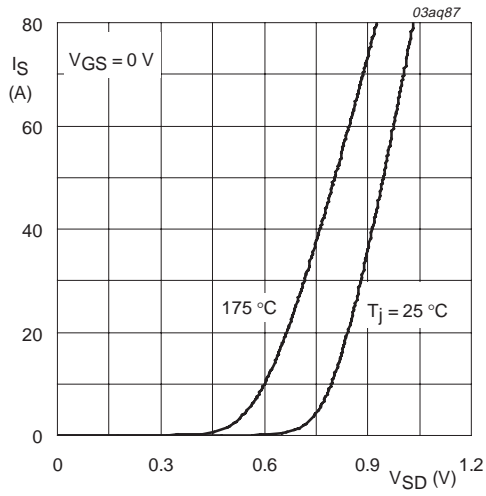
$T_j = 25 \text{ }^{\circ}C; V_{DS} = 5 \text{ V}$

Fig 10. Sub-threshold drain current as a function of gate-source voltage.



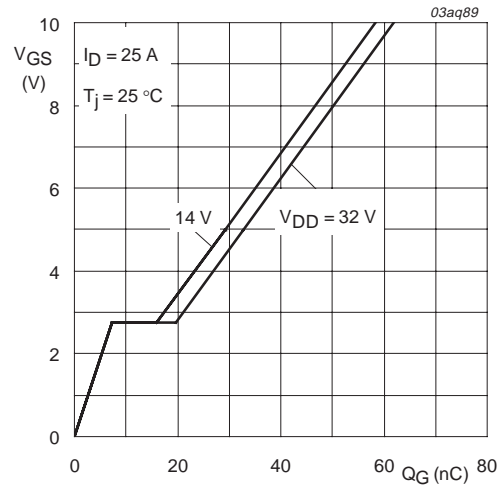
$V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$

Fig 11. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values.



$T_j = 25\text{ }^\circ\text{C}$ and $175\text{ }^\circ\text{C}$; $V_{GS} = 0\text{ V}$

Fig 12. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values.



$I_D = 25\text{ A}$; $V_{DD} = 14\text{ V}$ and 32 V

Fig 13. Gate-source voltage as a function of gate charge; typical values.

7. Package outline

Plastic single-ended surface mounted package (Philips version of D²-PAK); 3 leads (one lead cropped)

SOT404

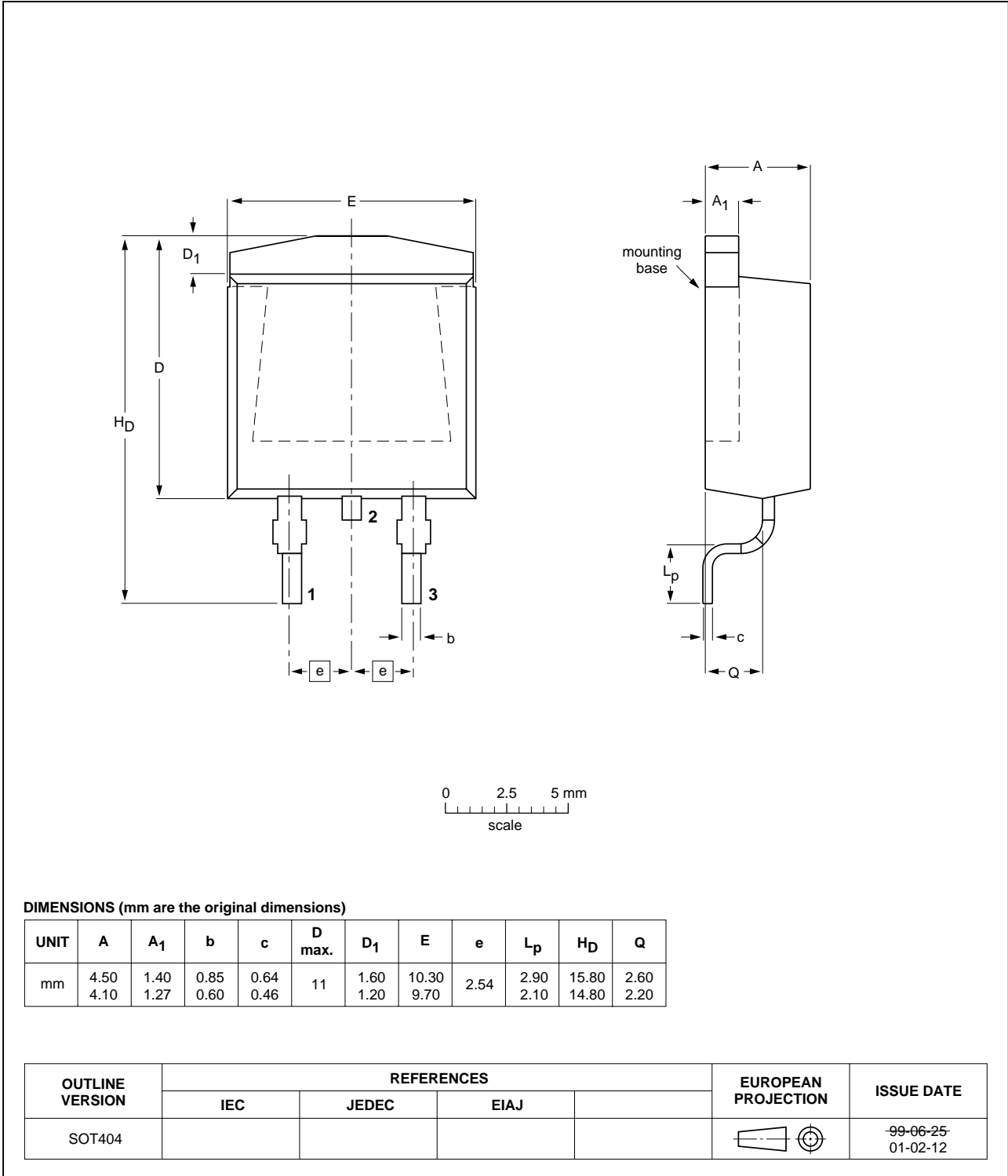


Fig 14. SOT404 (D²-PAK).

8. Revision history

Table 6: Revision history

Rev	Date	CPCN	Description
01	20040511	-	Product data (9397 750 13166)

9. Data sheet status

Level	Data sheet status ^[1]	Product status ^{[2][3]}	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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Contents

1	Product profile	1
1.1	Description	1
1.2	Features	1
1.3	Applications	1
1.4	Quick reference data	1
2	Pinning information	1
3	Ordering information	2
4	Limiting values	2
5	Thermal characteristics	4
5.1	Transient thermal impedance	4
6	Characteristics	5
7	Package outline	9
8	Revision history	10
9	Data sheet status	11
10	Definitions	11
11	Disclaimers	11
12	Trademarks	11

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